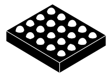
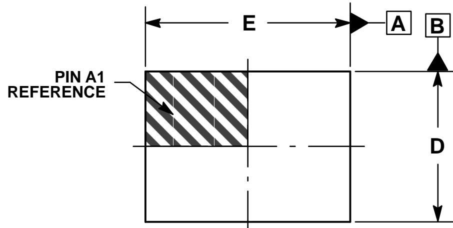
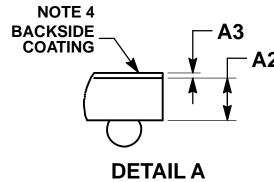


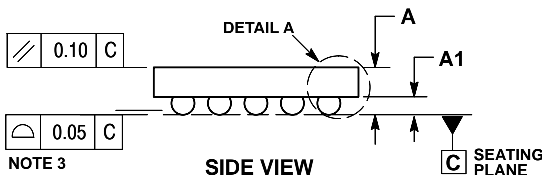
SCALE 4:1

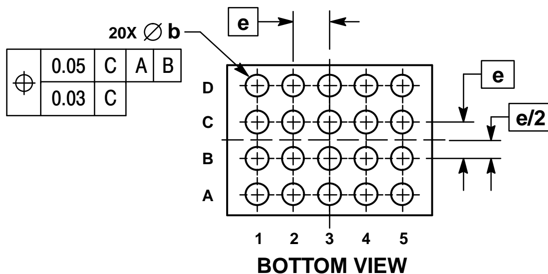
WLCSP20, 1.66x2.26x0.6
CASE 567PM
ISSUE O

DATE 09 AUG 2016

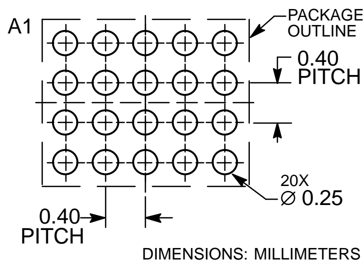








RECOMMENDED SOLDERING FOOTPRINT*

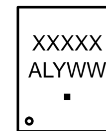


*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.
4. BACKSIDE COATING IS OPTIONAL.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	---	---	0.60
A1	0.179	0.199	0.219
A2	0.323	0.338	0.353
A3	0.017	0.022	0.027
b	0.241	0.271	0.301
D	1.61	1.66	1.71
E	2.21	2.26	2.31
e	0.40 BSC		

GENERIC MARKING DIAGRAM*



A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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NEW STANDARD:		
DESCRIPTION:	WLCSP20, 1.66X2.26X0.6	PAGE 1 OF 2

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